

NOTES:

- MATERIAL:  
HOUSING: LCP WITH 30% GF, UL94 V-0, BLACK COLOR.  
CONTACTS: PHOSPHOR BRONZE.  
PEGS: BRASS.
- FINISH:  
CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, WITH GOLD FLASH OVER 1.27µm [50µ"] MIN. NICKEL ON ENTIRE CONTACT.  
PEGS: 3.048µm [120µ"] MIN. MATTE-TIN OVER 1.27µm [50µ"] MIN. NICKEL.
- REFLOW SOLDER CAPABLE TO 260°C PER TEC-109-201, CONDITION B.

LOC	DIST	REVISIONS		DATE	BY	APP'D
DW		P	LHR			
		C	ECR-11-020284	040CT11	AW	WK

PCI-E MINI CARD CONNECTOR SIGNAL ASSIGNMENTS

PIN#	NAME	PIN#	NAME
51	Reserved	52	+3.3Vaux
49	Reserved	50	GND
47	Reserved	48	+15V
45	Reserved	46	LED_WPANH
43	GND	44	LED_WLANH
41	+3.3Vaux	42	LED_WWANH
39	+3.3Vaux	40	GND
37	GND	38	USB_D+
35	GND	36	USB_D-
33	PETp0	34	GND
31	PETn0	32	SMB_DATA
29	GND	30	SMB_CLK
27	GND	28	+15V
25	PERp0	26	GND
23	PERn0	24	+3.3Vaux
21	GND	22	PERST#
19	Reserved* (UIM_C4)	20	W_DISABLE#
17	Reserved* (UIM_C8)	18	GND

mSATA CONNECTOR SIGNAL ASSIGNMENTS

PIN#	NAME	PIN#	NAME
51	Presence Detection	52	+3.3V
49	DA/DSS	50	GND
47	Vendor	48	+15V
45	Vendor	46	Reserved
43	No Connect	44	Reserved
41	+3.3V	42	Reserved
39	+3.3V	40	GND
37	GND	38	Reserved
35	GND	36	Reserved
33	+A	34	GND
31	-A	32	Two Wire Interface
29	GND	30	Two Wire Interface
27	GND	28	+15V
25	-B	26	GND
23	+B	24	+3.3V
21	GND	22	Reserved
19	Reserved	20	Reserved
17	Reserved	18	GND

\* Reserved for future UIM interface (if needed)

TYPE II	0.254µm [10µ"]	2041119-4
	GOLD FLASH	2041119-3
TYPE I	0.254µm [10µ"]	2041119-2
	GOLD FLASH	2041119-1
PACKING TYPE	MIN. GOLD THICKNESS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DATE	05JAN2009	BY	A. HOU
CHK	S. HOU	DATE	05JAN2009
APP'D	W. KODAMA	DATE	05JAN2009
PRODUCT SPEC	108-99102	APPLICATION SPEC	
WEIGHT	1.18 GRAMS	SIZE	A2
CUSTOMER DRAWING		CASE CODE	00779

**TE Connectivity**

**2 in 1 mSATA & PCI EXPRESS MINI CARD CONNECTOR, 4 MM HEIGHT**

SCALE: — SHEET: 1 of 5





4

3

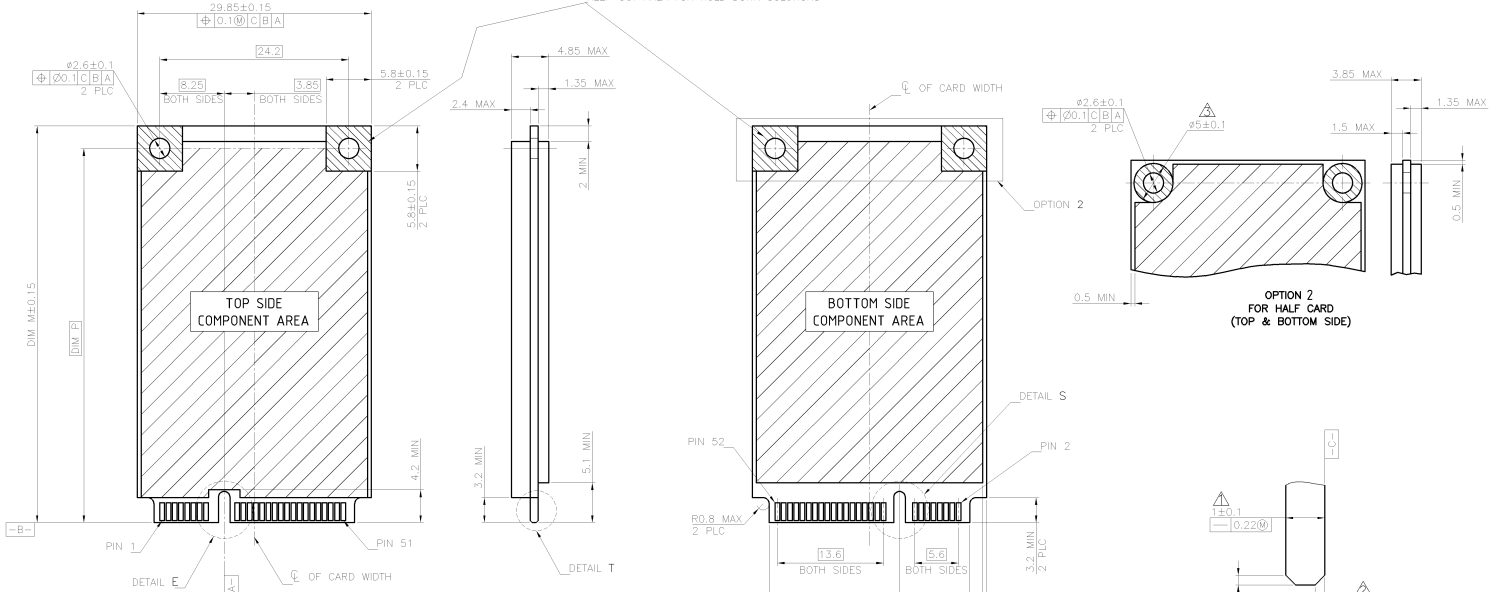
2

1

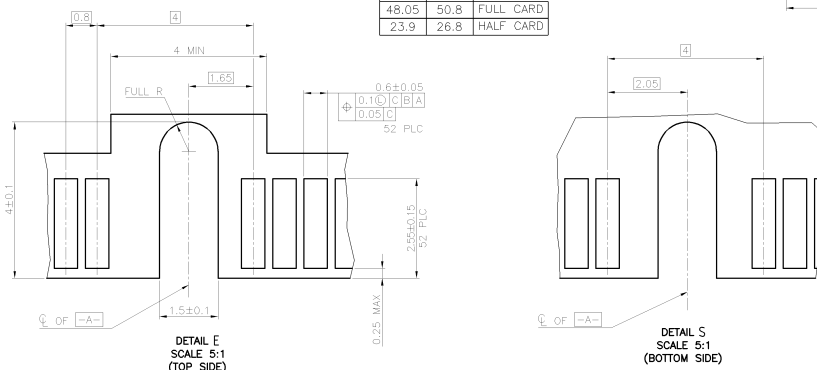
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LOC	DIST	REVISIONS	DATE	OWN	APP'D
DW					
		DESCRIPTION			
		SEE SHEET 1			

COMPONENT AND ROUTING (ALL LAYERS)  
 KEEP OUT AREA FOR HOLD DOWN SOLUTIONS



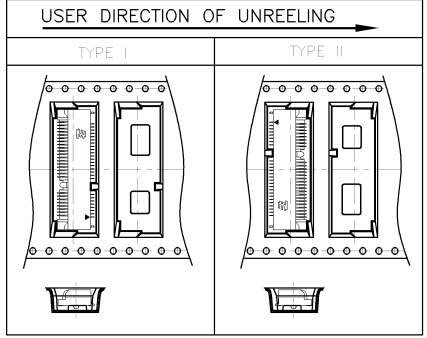
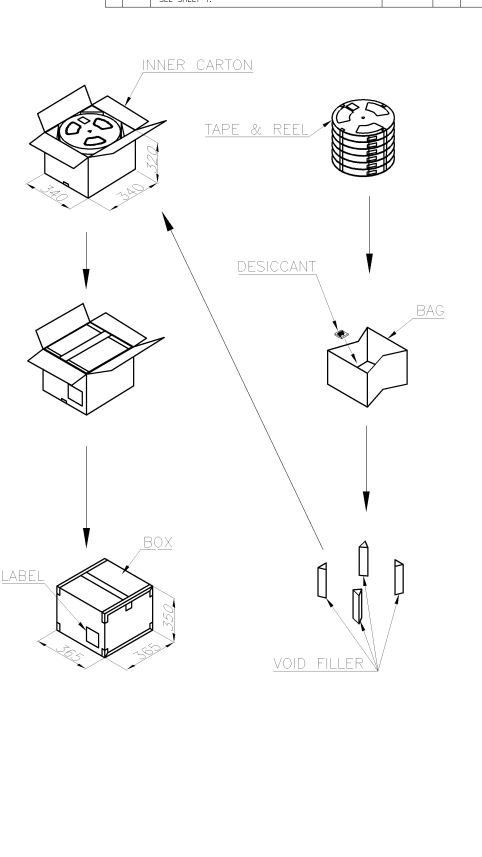
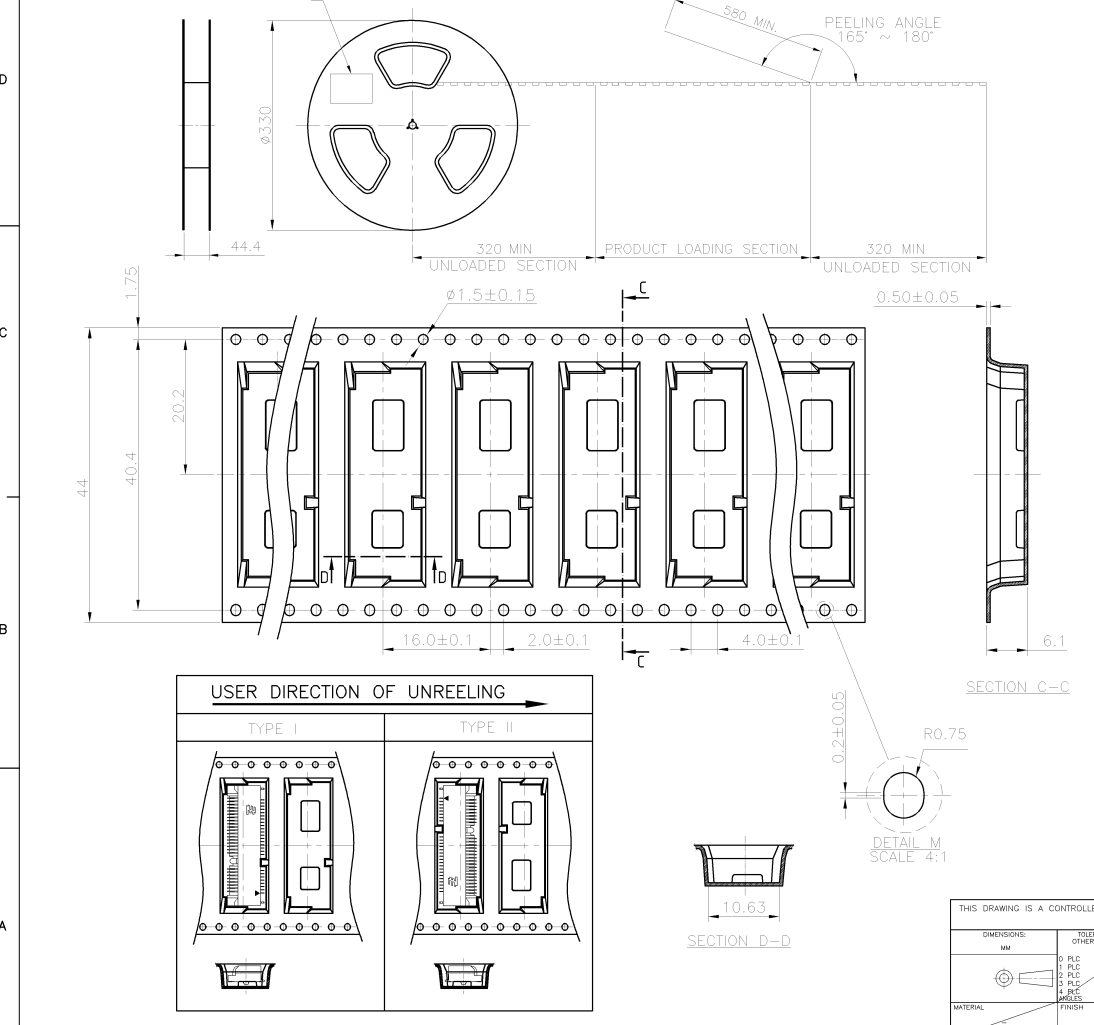
DIM P	DIM M	FULL CARD	HALF CARD
48.05	50.8		
23.9	26.8		



- NOTES:
- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
  - △ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING BURRS FROM PCB AND CONTACT MATERIALS.
  - △ COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.

FOR mSATA

THIS DRAWING IS A CONTROLLED DOCUMENT.		TE Connectivity	
DIMENSIONS: MM DIMENSIONS: INCH		DW: DW CHK: CHK DATE: DATE NAME: NAME PRODUCT SPEC: PRODUCT SPEC APPLICATION SPEC: APPLICATION SPEC HEIGHT: HEIGHT	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0. PLG ± .05 1. PLG ± .05 2. PLG ± .05 3. PLG ± .05 4. PLG ± .05 5. PLG ± .05		SIZE: A2 CASE CODE: 00779 DRAWING NO: C-2041119 RESTRICTED TO:	
MATERIAL: MATERIAL		CUSTOMER DRAWING	
FINISH: FINISH		SCALE: SCALE SHEET: 4 of 5 REV: C	



THIS DRAWING IS A CONTROLLED DOCUMENT.		DW		CHK		APVD		NAME	
DIMENSIONS: MM		TOLERANCES UNLESS OTHERWISE SPECIFIED:		PRODUCT SPEC		APPLICATION SPEC		REVISIONS	
MATERIAL		FINISH		HEIGHT		SIZE		RESTRICTED TO	
						A2		CUSTOMER DRAWING	
						00779		SCALE	
						C=2041119		SHEET 5 of 5	
								REF C	

3900 PCS	650	6	9.50	4.618
QUANTITY	PCS/TWIST	REELS/BOX	G/W(Kg)	N/W(Kg)

**TE** TE Connectivity

2 IN 1 mSATA & PCI EXPRESS MINI CARD CONNECTOR, 4 MM HEIGHT